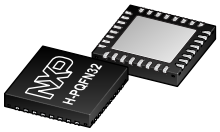
SOT617-30(DD)

H-PQFN32, thermal enhanced - plastic quad flat non-lead, 32 terminals, 0.5 mm pitch, 5 mm x 5 mm x 0.85 mm body

22 June 2026 Package information



1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	H-PQFN32
Package style descriptive code	H-PQFN (thermal enhanced - plastic quad flat non-lead)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	30-10-2024
Manufacturer package code	98ASA02234D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	4.9	5	5.1	mm
package width	4.9	5	5.1	mm
seated height	0.8	0.85	1	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	32	-	

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2 Package outline

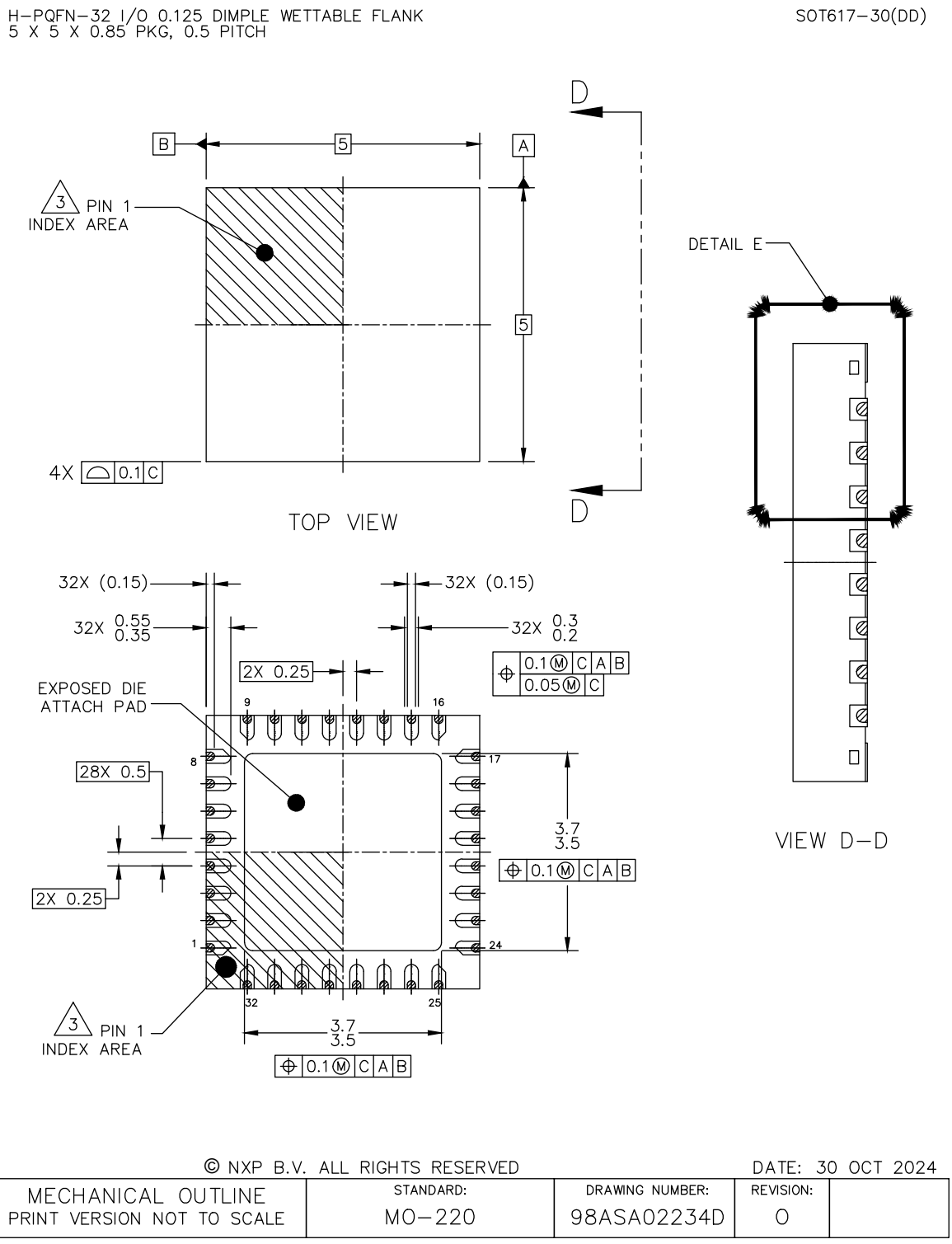
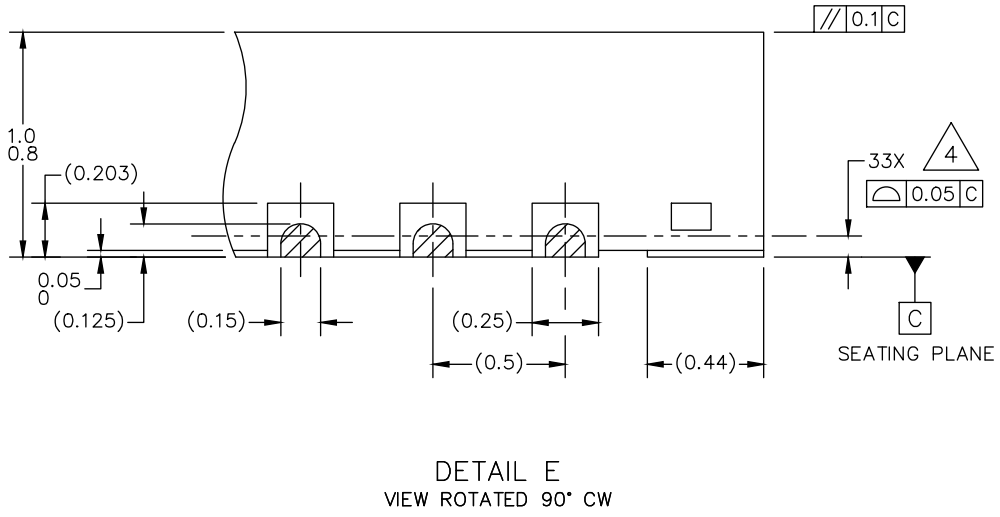


Figure 1. Package outline H-PQFN32 (SOT617-30(DD))



DATE: 30 OCT 2024

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: MO–220	DRAWING NUMBER: 98ASA02234D	REVISION: O	

Figure 2. Package outline detail E of H-PQFN32 (SOT617-30(DD))

3 Soldering

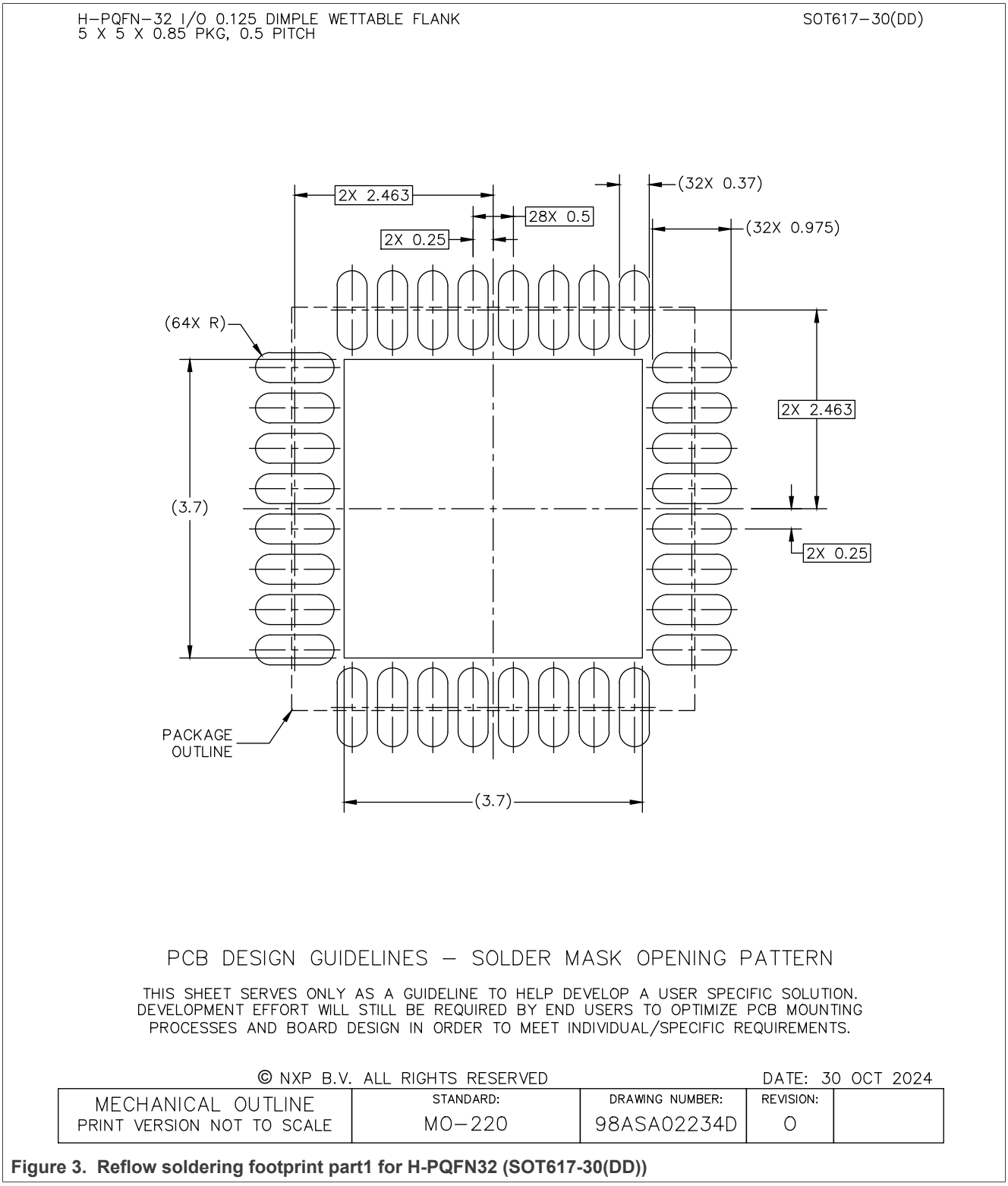
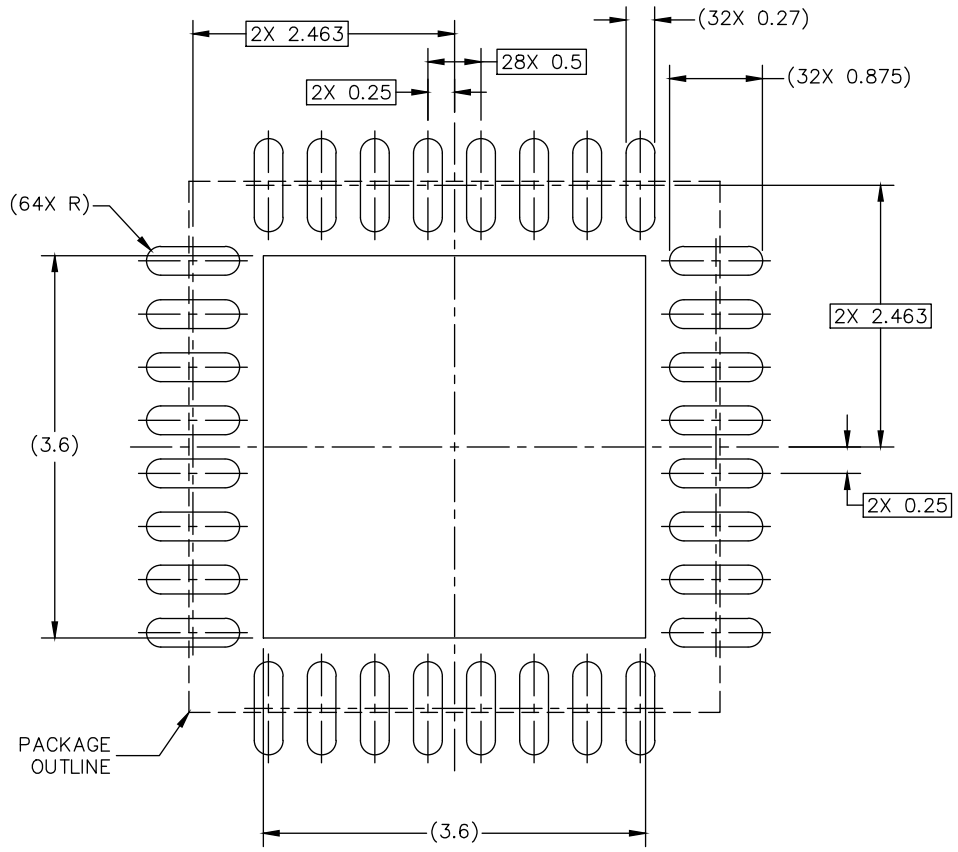


Figure 3. Reflow soldering footprint part1 for H-PQFN32 (SOT617-30(DD))

H-PQFN-32 I/O 0.125 DIMPLE WETTABLE FLANK
5 X 5 X 0.85 PKG, 0.5 PITCH

SOT617-30(DD)



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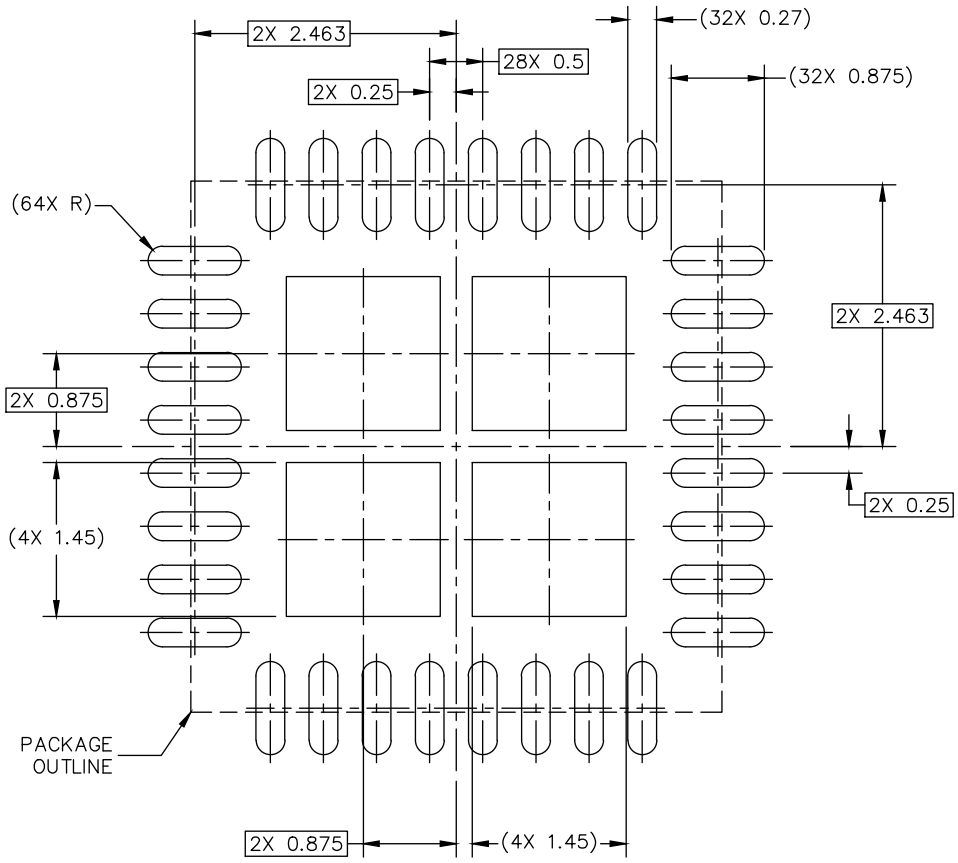
DATE: 30 OCT 2024

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: MO-220	DRAWING NUMBER: 98ASA02234D	REVISION: O	

Figure 4. Reflow soldering footprint part2 for H-PQFN32 (SOT617-30(DD))

H-PQFN-32 I/O 0.125 DIMPLE WETTABLE FLANK
5 X 5 X 0.85 PKG, 0.5 PITCH

SOT617-30(DD)



RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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DATE: 30 OCT 2024

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: MO-220	DRAWING NUMBER: 98ASA02234D	REVISION: O	

Figure 5. Reflow soldering footprint part3 for H-PQFN32 (SOT617-30(DD))

H-PQFN32, thermal enhanced - plastic quad flat non-lead, 32 terminals, 0.5 mm pitch, 5 mm x 5 mm x 0.85 mm body

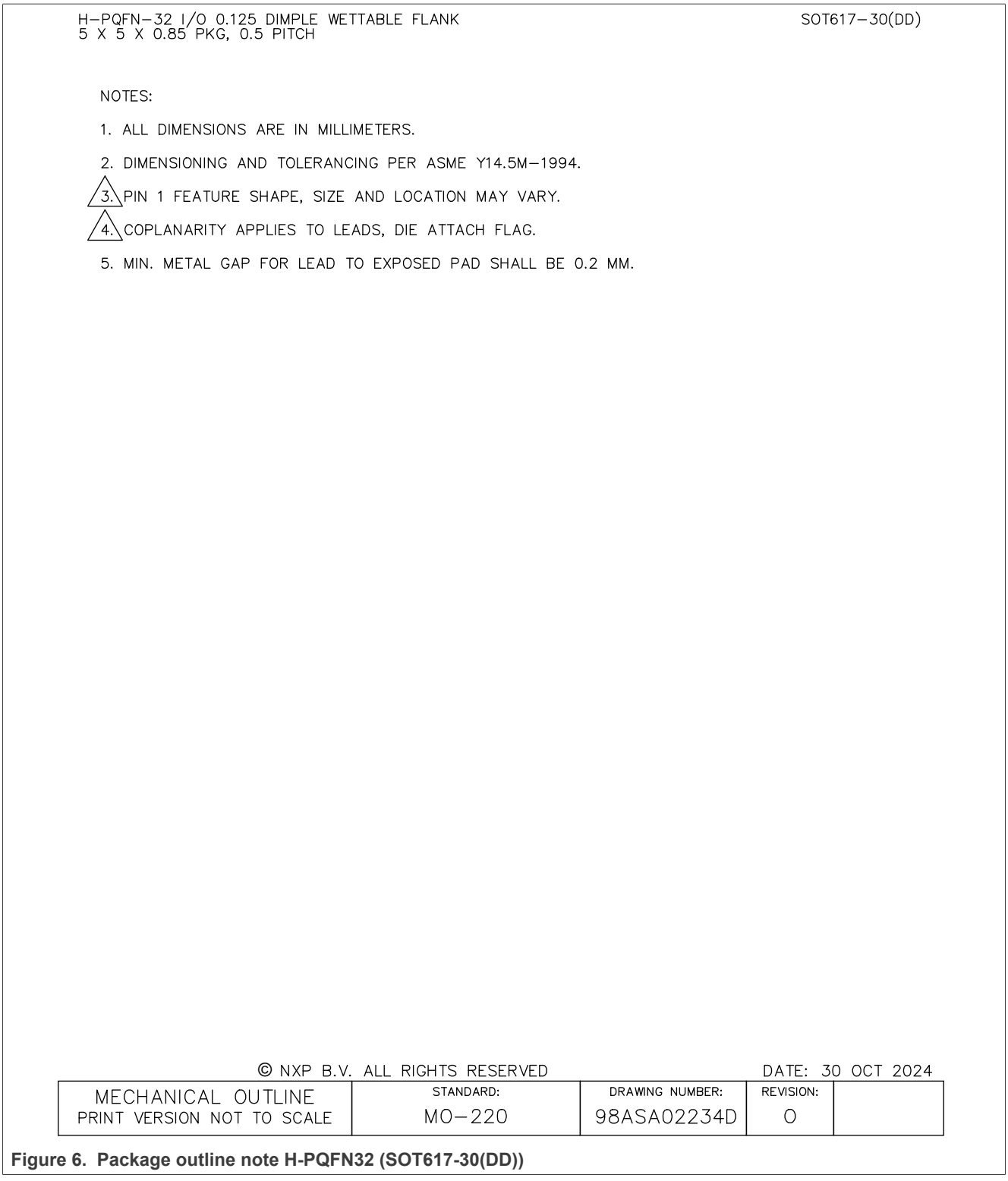

Figure 6. Package outline note H-PQFN32 (SOT617-30(DD))

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